

HBS Special Session <The speakers will be announced shortly.>

	Room A
13:00	
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15:10	
15:30	
16:00	
16:30	

	Room A	Room B	Room C	Room D	Room E	Room F
9:00	15WA1: INEMI 15WA1-1 Testing and Characterization for Semiconductor Packaging Thermal Management Dongkai Shangguan ¹ , Chun Keang Ooi ² , Sze Pei Lim ¹ , ¹ Indium Corporation, ² Intel, ³ Thermal Engineering Associates, Inc. 15WA1-2 Benchmarking AOI Capabilities for Fine Pitch Substrate Inspection Feng Xue ¹ , Charles Reynolds ² , Glenn Pomerantz ² , Jason Frankel ² , Thomas Wassick ² , Charlie Zhu ² , Masahiro Tsuruya ² , ¹ IBM, ² IBM Corp, ³ Nordson T&L, ⁴ INEMI 15WA1-3 Thermal Stress Study of Low Temperature Material for 1st Level Interconnect Sze Pei Lim ¹ , Danyang Zheng ¹ , Russell Kastberg ² , Shripad Gokhale ² , Yasuharu Yamada ² , Masaki Sanada ² , Takumi Miyazaki ² , Kei Murayama ² , Masahiro Tsuruya ² , ¹ Indium Corporation, ² IBM Infrastructure, ³ Intel Corporation, ⁴ IBM Research, ⁵ Shinko Electric Industries, ⁶ INEMI 15WA1-4 Warpage Experiments and Simulation for Glass Core Substrate Kang Eu Ong ¹ , Konishi Junko ² , Satake Noboru ² , Sato Yoichiro ² , Yoshida Tatsuro ² , Murayama Kei ² , Tsukahara Makoto ² , Haley Fu ² , ¹ Intel Technology, ² AGC, ³ Shinko, ⁴ Inemi	15WB1: EPTC 15WB1-1 <Session Invited> TBD 15WB1-2 <Session Invited> TBD 15WB1-3 <Session Invited> TBD 15WB1-4 <Session Invited> TBD	15WC1: Fanout Packing-1 15WC1-1 Advanced Panel Level Fan Out Package - Development of a Damascene Integration Scheme for Cu Redistribution Layers Eungchul Kim, Suhyeon Jeon, Jusuk Kang, Sanghoon Cho, Jeongmin Seo, Dongjeon Oh, Juil Choi, Minwoo Rhee, Samsung Electronics 15WC1-2 From Pilot To HVM A Practical Overlay Yield Prediction Workflow For FOPLP Lithography John Chang, Jian Lu, Timothy Chang, Onto Innovation 15WC1-3 TRC and Fusing current Characterization of Cu RDL Lines for Fan-Out Wafer-Level Packaging Fayong Liu ¹ , Jinbiao Hu ¹ , I-Hung Lin ² , Maple Jiang ³ , Jinyan Nan ¹ , Ryan Pang ³ , Dongdong Niu ¹ , Yinhan Zhao ¹ , Qianyu Jia ¹ , Kaidi Sun ¹ , Haiyong Zheng ¹ , Tom Ni ² , ¹ Ocean University of China, ² Kore Semiconductor Co., Ltd 15WC1-4 Approach of graphic dynamic adjustment integrate to Laser direct imaging solution on 600um Panel Fan Out PING CHING Shen, Jen-Kuang Fang, Ping-Feng Yang, Sheng-Feng Huang, Advanced Semiconductor Engineering, Inc.	15WD1: HB Process 15WD1-1 <Session Invited> TBD 15WD1-2 <Session Invited> TBD 15WD1-3 Simplified Gap-Filling Process for Reconstructed Die-to-Wafer Hybrid Bonding Using Spin-Coated Silicone Resin Asuka Fujii ^{1,2} , Yutetsu Kamiya ¹ , Kenta Hayama ¹ , Fumihiro Inoue ² , ¹ Yokohama National University, ² ADEKA Corporation 15WD1-4 Prediction of High-Temperature Expansion of Cu in SiO2 Vias for Fine-Pitch Hybrid Bonding 3D-IC Applications Pin-Lin Chen ¹ , Chih Chen ^{1,2} , ¹ Institute of Pioneer Semiconductor Innovation, National Yang Ming Chiao Tung University, ² Department of Materials Science and Engineering, National Yang Ming Chiao Tung University	15WE1: Materials-1 15WE1-1 Electro-Plating of Sn-Cu-Ni Based IMC Material for Connectors and Switches Hiroaki Ikeda, Shigenobu Sekine, Napra, Co. Ltd. 15WE1-2 Cu3Sn as a Passivation Layer for Improving Reliabilities of Nanotwinned Cu Interconnects Jing Chok, Chih Chen, Yi-Quan Lin, National Yang Ming Chiao Tung University 15WE1-3 Strengthening of Pressureless Ag Sintering with (111)-Oriented Nanotwinned Cu Substrate Zhi-Quan Liu ¹ , Shubo Ai ¹ , Xingming Huang ² , ¹ Southern Institutes of Science and Technology, ² Shenzhen Institutes of Advanced Technology, Chinese Academy of Sciences 15WE1-4 Electric Current Becomes a Thermodynamic Variable - Revisiting Phase Stability in Alloys Shubhayan Mukherjee, Shih-Kang Lin, National Cheng Kung University	15WF1: Emerging Technologies-1 15WF1-1 <Session Invited> Proposal of Development of Megawatt Super-Power Operational Amplifier Using Distar Transistor Kensho Okamoto ¹ , Ken-ichiro Okamoto ² , Kazunori Morishita ³ , Atsushi Okuno ⁴ , ¹ Kagawa University, ² Kyoto University, ³ Green Planets Co. 15WF1-2 Microstructure Evolution and Strength Improvement in Cu-to-Cu Bonding with Micro/Nano Cu Paste ALBERT TZUCHUA WU ¹ , Li-Chen Wu ¹ , Shao-Chi Chen ¹ , Kelvin Li ² , Chang-Meng Wang ² , ¹ National Central University, ² Shenmao Technology INC. 15WF1-3 Via-Last Bumpless TSV for High Bandwidth NAND (HBN) Koji Sakui, Norio Chujo, Masao Taguchi, Takayuki Ohba, Institute of Science Tokyo 15WF1-4 Localized plastic deformation analysis of fordable substrates by using micro-digital image correlation Nakyung JEONG ¹ , Jeehoon Na, Eunhye Lee, Sojeong Lee, Tae-Ik Lee, Korea Institute of Industrial Technology
10:40	Break					
10:55	15WA2: MEF 15WA2-11 <Session Invited> My 40 years with MEMS, leading to mutual contribution of MEMS/Semiconductors Susumu Kaminaga, Toray Industries, Inc./SK Global Advisers Co., Ltd. 15WA2-2 <Session Invited> Development of Automotive Chiplet SoC Nobuaki Kawahara, PhD, ASRA, Advanced SoC Research for Automotive 15WA2-3 <Session Invited> Compact FT-NIR spectrometer made through MOEMS technology Tomofumi Suzuki, HAMAMATSU PHOTONICS K.K.	15WB2: IMAPS 15WB2-1 <Session Invited> TBD 15WB2-2 <Session Invited> TBD 15WB2-3 <Session Invited> TBD 15WB2-4 <Session Invited> TBD	15WC2: Fanout Packing-2 15WC2-1 A Novel Fan-Out Wafer Module Stacking Technology Using Transfer Bonding Chih-Cheng Hsiao, Industrial Technology Research Institute 15WC2-2 Warpage Prediction in Multi-Layer Fan-Out Panel-Level Packaging Using Finite Element Method with Artificial Neural Network Chen-Chen Li, Kuo-Shen Chen, National Cheng-Kung University, Department of Mechanical Engineering 15WC2-3 Advanced Packaging Solution by Large Panel Level Fan-out Process for High Performance Computing application Powei Lu, Jeffrey Yang, Yungshun Chang, Yuan Feng Chiang, Jen Kuang Fang, Advanced Semiconductor Engineering 15WC2-4 New Advanced Packaging Architecture - CoWoP (Chip on Wafer on Platform PCB) Terry Hsu, Huei-Chi Yang, Sam Lin, Vito Lin, Andrew Kang, Don Son Jiang, Siliconware Precision Industries Co., Ltd.	15WD2: Solder/Intermetallic connect 15WD2-1 <Session Invited> Innovative Materials for Advanced Packaging and Heterogeneous Integration Dongkai Shangguan, Sze Pei Lim, Indium Corporation 15WD2-2 Investigating Interfacial Reactions and Shear Strength of SnAg / Fe-HEA Alloy Tzu-Hsiang Liao ¹ , Jia-Xiang Gao ¹ , Chuh-Hsiang Liu ¹ , Chuan Zhang ² , Yu-An Shuai ¹ , Feng Chia University, ³ CompTherm LLC 15WD2-3 Interfacial Diffusion Control in Silver-Indium Transient Liquid Phase Bonding with Two-Dimensional Interlayers Jiaqi Song ¹ , Donglin Zhang ¹ , Xuochen Zhao ¹ , Gang Zhang ² , Yongjun Huo ^{2,3} , ¹ School of Materials Science and Engineering, Beijing Institute of Technology, ² Yangtze River Delta Graduate School of Beijing Institute of Technology, ³ Shenzhen MSU-BIT University, Department of Materials Science 15WD2-4 Development and Characterization of Eco-Friendly Sn-Ag-Cu-Zn Solder for Electrical Performance on PCB Applications Andromeda Dwi Laksono ^{1,2} , Muhammad Ramanda Putra ¹ , Nurkholis Majid ¹ , Muhammad Mahessa Ajibasa Syaaban ¹ , Devit Velanti Putra ¹ , Lusi Enawati ^{1,2} , ¹ Muhammad Ridho Devanto ¹ , ² Kharis Sugianto ¹ , ³ Study Program of Materials and Metallurgical Engineering, Institut Teknologi Kalimantan, ⁴ Center for Green Materials Innovation, Institut Teknologi Kalimantan, ⁵ Department of Chemical Engineering, Institut Teknologi Kalimantan, ⁶ Department of Electrical Engineering, Institut Teknologi Kalimantan	15WE2: Materials-2 15WE2-1 Ultra-Thick Photoresist Patterning Enabling Higher Aspect Ratio Cu Posts for Advanced Packaging Tatsuya Fujii, Issei Suzuki, Kazuki Hirano, Eiichi Hayashi, Nobuya Takahashi, Toshiaki Furutani, Takashi Kariya, Samsung Device Solutions R&D Japan, Samsung Japan Corporation 15WE2-2 Investigation of SiCN-SiCN bonding with different wet pretreatment solutions followed by O2 plasma for Cu/SiCN hybrid bonding application Chien-Yu Liu ¹ , Chih Chen ^{1,2} , Pin-Syuan He ¹ , Yun-Hsuan Chen ¹ , Rou-Jun Lee ² , Gyanu Song ² , Cheng Chieh Kao ² , ¹ Department of Materials Science and Engineering, National Yang Ming Chiao Tung University, ² Industry Academia Innovation School, National Yang Ming Chiao Tung University, ³ Lam research Corporation, Tualatin, Oregon, 97062, ⁴ Lam research Corporation, 1F,No22,R&D RD,II, Hsinchu Science Park 15WE2-3 Reliability Study of NMP-Free PI with Anti-Metal Migration Properties Daniel Chen, Wei-Chun Chen, Renata Hsiao, Fenny Liu, Allen Huang, Liang-Yih Hung, Andrew Kang, Siliconware Precision Industries Co., Ltd. [15WE2-4] Fine Trench Fabrication by Excimer Laser Ablation and Plasma Etching Kento Eguchi,Masatsugu Nakano,Eiichiro YamasakiShin-Etsu Engineering Co., Ltd.,	15WF2: Emerging Technologies-2 15WF2-1 <Session Invited> AI-powered analytics for interconnect technologies utilized in electronic packaging Roland Brunner, Materials Center Leoben Forschung GmbH 15WF2-2 High-Resolution 3D Printed Microelectronics Platform for Advanced Packaging Applications Hylike Akkerman, Jeroen Sol, Darragh Walsh, Peter Rensing, Sophie Suijldendorp, Holst Centre / TNO 15WF2-3 Investigation of Laser Parameters for the Creation of Traces and Contact Pads on Aluminum Nitride Ceramics Finn-Merlin Deckert, Cathleen Kleinholz, Christoph Heinze, Indra Kaeplinger, Thomas Ortlepp, CIS Forschungsinstitut fuer Mikrosensorik GmbH 15WF2-4 Cu Pillar Chip Bonding using 3D-Printed Fan-Out Substrate for Advanced Packaging Haksoon Jung, Jimin Kwon, Ulsan National Institute of Science and Technology (UNIST)
12:35	Lunch					
12:55	Luncheon Talk: TBD					
13:25	Break / Poster Session					
13:35	Break					
14:50	Award Ceremony					
15:00	Break					
15:30	Keynote Lecture I: TBD					
15:40	Keynote Lecture II: TBD					
16:40	Introduction to ICEP 2027					
17:40	Welcome Reception (Grand Prince Hotel Hiroshima)					
17:45						
18:15						
20:15						